

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7210166

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SAMSUNG ELECTRONICS CO., LTD.	02/18/2022
RECEIVING PARTY DATA	
Name:	INTERNATIONAL SEMICONDUCTOR GROUP
Street Address:	1231, 15, TEHERAN-RO 82-GIL, GANGNAM-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	8953509
CORRESPONDENCE DATA	
Fax Number:	(202)403-3587
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	202-293-0804
Email:	usdocketing@jeffersonip.com
Correspondent Name:	JEFFERSON IP LAW, LLP
Address Line 1:	1130 CONNECTICUT AVE., NW, SUITE 420
Address Line 4:	WASHINGTON, D.C. 20036
ATTORNEY DOCKET NUMBER:	0203-0773
NAME OF SUBMITTER:	MAENG-HO SHIN
SIGNATURE:	/Maeng-Ho SHIN/
DATE SIGNED:	03/07/2022
Total Attachments: 5	
source=0203-0773AssignmentAsFiled#page1.tif	
source=0203-0773AssignmentAsFiled#page2.tif	
source=0203-0773AssignmentAsFiled#page3.tif	
source=0203-0773AssignmentAsFiled#page4.tif	
source=0203-0773AssignmentAsFiled#page5.tif	

RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)
 Samsung Electronics Co., Ltd.

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)
 Name: International Semiconductor Group
 Internal Address: _____
 Street Address: 1231, 15, Teheran-ro 82-gil, Gangnam-gu
 City: Seoul
 State: _____
 Country: Republic of Korea Zip: 06178

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance/Execution Date(s):
 Execution Date(s) February 18, 2022

Assignment Merger
 Security Agreement Change of Name
 Joint Research Agreement
 Government Interest Assignment
 Executive Order 9424, Confirmatory License
 Other _____

4. Application or patent number(s): This document is being filed together with a new application.

A. Patent Application No. (s) _____ B. Patent No. (s) 8,953,509

Additional numbers attached? Yes No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Jefferson IP Law, LLP
 Internal Address: Maeng-Ho SHIN
 Street Address: 1130 Connecticut Ave., NW, Suite 420
 City: Washington
 State: DC Zip: 20036
 Phone Number: 202-293-0804
 Fax Number: 202-403-3587
 Email Address: usdocketing@jeffersonip.com

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ _____

Authorized to be charged by credit card
 Authorized to be charged to deposit account
 Enclosed
 None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
 Expiration Date _____

b. Deposit Account Number _____
 Authorized User Name _____

9. Signature: _____ /Maeng-Ho SHIN/ Reg. #53,859 _____ March 7, 2022
 Signature Date

Maeng-Ho Shin
 Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 5

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

APPENDIX I
Deed of Assignment

This Deed of Assignment is made this ____ day of February, 2022 between Samsung Electronics Co., Ltd., having its registered office in Suwon, Korea ("Assignor") and International Semiconductor Group, having its registered office in Seoul, Korea ("Assignee").

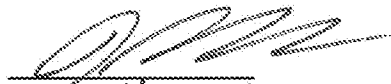
WHEREAS, Assignor and Assignee have agreed on the transfer and assignment of Assignor's entire rights, title and interest in and to the patents and patent applications attached to this deed of assignment ("Assigned Patents").

NOW THEREFORE for good and valuable consideration, receipt of which is hereby acknowledged, Assignor hereby confirms the assignment and transfer to Assignee of all Assignor's worldwide right, title, and interest in and to the Assigned Patents, to be held and enjoyed by Assignee, in its full discretion, including but not limited to all rights, if any, to (A) register or apply in all countries and regions for patents, utility models and like rights of exclusion and for inventors' certificates for the subject matters of the Assigned Patents; (B) prosecute, maintain and defend the Assigned Patents and any registrations or applications relating to the subject matters of the Assigned Patents before any public or private agency, office or registrar including by filing reissues, reexaminations, divisions, continuations, continuations-in-part, substitutes, extensions and all other applications and post issue proceedings in relation to the Assigned Patents; and (C) claim priority based on the filing dates of any of the Assigned Patents under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, the Paris Convention, and all other treaties of like purposes. Assignee agrees to (1) grant to Assignor and its affiliates a non-exclusive, perpetual, world-wide, royalty free, non-transferable and irrevocable license, under the Assigned Patents, to develop, have developed, make, have made, use, sell, offer for sale, distribute, import and otherwise exploit any products (including software), services, methods and processes to manufacture, test or examine and (2) comply with all prior commitments and prior undertakings vis-à-vis third parties entered into by Assignor pertaining to the Assigned Patents.

IN WITNESS WHEREOF, Assignor has executed this Deed of Assignment. The person signing this Deed of Assignment on behalf of Assignor represents that he/she is fully authorised to execute this Deed of Assignment on behalf of Assignor.

Assignor:

Samsung Electronics Co., Ltd.



Name: Heiim CHANG

Title: EVP

Date: Feb 18 2022

EXHIBIT C
Patent Transfer under Section 5(a)(ii)

Application	Patent	Country
07108648.2	1912096	DE
07108648.2	1912096	GB
07108648.2	1912096	NL
200710136657.0	ZL200710136657.0	CN
US11/688293	US7962032	US
08766388.6	2168327	DE
08766388.6	2168327	GB
08766388.6	2168327	NL
08753668.6	2168305	DE
08753668.6	2168305	GB
08753668.6	2168305	NL
2005323613	2005323613	AU
2569203	2569203	CA
3539/KOLNP/2006	258700	IN
2006145869	2350016	RU
05013840.3	1612998	DE
05013840.3	1612998	FR
05013840.3	1612998	GB
200410033301.0	ZL200410033301.0	CN
04008103.6	1465134	DE
04008103.6	1465134	FR
04008103.6	1465134	GB
US11/171364	US8872843	US
200810174266.2	ZL200810174266.2	CN
05014455.9	1612736	DE
05014455.9	1612736	GB
200510078371.2	ZL200510078371.2	CN
05013274.5	1608137	DE
05013274.5	1608137	FR
05013274.5	1608137	GB
05011764.7	1603312	DE
05011764.7	1603312	FR
05011764.7	1603312	GB
US11/637321	US7813379	US
US12/856281	US7983305	US
07106136.0	1858279	DE
07106136.0	1858279	FR
07106136.0	1858279	GB
200710102826.9	ZL200710102826.9	CN
US13/206878	US8839149	US
P20100114907	P1726606	KR
1-2013-01851	17017	VN
US14/329066	US10162482	US
PI2013700542	MY-165364-A	MY
2013-532730	5905893	JP
1-2013-01440	21168	VN
2012231990	2012231990	AU
201280013479.1	ZL201280013479.1	CN

2013143025	2603527	RU
2013/07326	2013/07326	ZA
201210240659.5	ZL201210240659.5	CN
US13/490794	US8953509	US
201210238557.X	ZL201210238557.X	CN
12175838.7	2549725	DE
12175838.7	2549725	IT
2012248986	2012248986	AU
2013153097	2615059	RU
201210129082.0	ZL201210129082.0	CN
US13/418592	US8972176	US
2013206371	2013206371	AU
13172555.8	2677413	DE
201310250064.2	ZL201310250064.2	CN
2013-130401	6625312	JP
2014201509	2014201509	AU
201410095287.0	ZL201410095287.0	CN
14159941.5	2778988	DE
14159941.5	2778988	GB
14159941.5	2778988	NL
14175884.7	2824561	DE
14175884.7	2824561	GB
14175884.7	2824561	NL
US14/322170	US10331329	US
14159637.9	2778865	DE
14159637.9	2778865	GB
14159637.9	2778865	NL
14161418.0	2784690	DE
14161418.0	2784690	GB
14161418.0	2784690	NL
14172564.8	2830263	DE
14172564.8	2830263	GB
14172564.8	2830263	NL
15158577.5	2922077	DE
15158577.5	2922077	GB
15158577.5	2922077	NL
14173892.2	2830264	DE
14173892.2	2830264	GB
14173892.2	2830264	NL
09773722.5	2291967	DE
09773722.5	2291967	GB
5014/KOLNP/2010	329235	IN
09773722.5	2291967	NL
200710136082.2	ZL200710136082.2	CN
07112533.0	1879206	DE
07112533.0	1879206	FR
07112533.0	1879206	GB
201080027662.8	ZL201080027662.8	CN
9489/CHENP/2011	311597	IN
201410054360.X	ZL201410054360.X	CN
US14/789634	US10067656	US
16172996.7	3112991	DE
16172996.7	3112991	GB

16172996.7	3112991	NL
201580037514.7	ZL201580037514.7	CN
15818851.6	3167358	DE
15818851.6	3167358	GB

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RECORDED: 03/07/2022

PATENT
REEL: 059184 FRAME: 0468